



Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
700V	580mΩ@10V	8A

Feature

- Super-Junction MOSFET
- High Ruggedness
- Low RDS(ON)
- 100% Avalanche Tested
- Improved dv/dt Capability

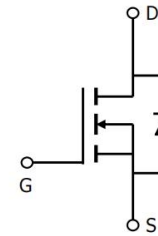
Application

- Charger
- PC Power
- LED Lighting

TO-252-2L



Schematic diagram



Package Marking and Ordering Information

Part Number	Package	Marking	Packing	Reel Size	Tape Width	Qty
GPJ70R580TF	TO-252-2L	J75R580	Tape&Reel	330mm	16mm	2500pcs

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain - Source Voltage	V_{DS}	700	V
Gate - Source Voltage	V_{GS}	±30	V
Continuous Drain Current ¹	$T_C = 25^\circ\text{C}$	I_D	8
	$T_C = 100^\circ\text{C}$	I_D	5
Pulsed Drain Current ¹	I_{DM}	24	A
Single Pulsed Avalanche Energy ³	E_{AS}	120	mJ
Repetitive Avalanche Energy ²	E_{AR}	10	mJ
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	104
MOSFET dv/dt Ruggedness($V_{DS}=0\sim 480\text{V}$)	dv/dt	50	V/ns
Peak Diode Recovery dv/dt($V_{DS}=0\sim 400\text{V}$, $I_{SD}\leq I_D$)	dv/dt	15	V/ns
Thermal Resistance, Junction to Case	R_{thjc}	1.2	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Ambient	R_{thja}	62	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	-55~ +150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~ +150	$^\circ\text{C}$

MOSFET ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D = 250μA	700			V
Breakdown Voltage Temperature Coefficient	ΔBV _{DSS} /ΔT _J	I _D =250uA, referenced to 25°C		0.56		V/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 700V, V _{GS} = 0V			1	μA
		V _{DS} = 560V, T _J =125°C			50	μA
Gate - Body Leakage Current	I _{GSS}	V _{GS} = ±30V, V _{DS} = 0V			±100	nA
On Characteristics						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	2.8	3.3	3.8	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 4A		500	580	mΩ
Forward Transconductance	G _{fs}	V _{GS} = 30V, I _D = 4.5A		7		S
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = 200V, V _{GS} = 0V, f = 1MHz		510		pF
Output Capacitance	C _{oss}			25		
Reverse Transfer Capacitance	C _{rss}			1.6		
Gate Resistance	R _g	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz		19		Ω
Switching Characteristics						
Total Gate Charge	Q _g	V _{DS} =560V, V _{GS} = 10V, I _D = 8A		15.6		nC
Gate-Source Charge	Q _{gs}			4.95		
Gate-Drain Charge	Q _{gd}			5.52		
Turn-On Delay Time	t _{d(on)}	V _{DS} =350V, V _{GS} = 10V, I _D = 8A, R _θ = 10Ω		12		ns
Turn-On Rise Time	t _r			24		
Turn-Off Delay Time	t _{d(off)}			30		
Turn-Off Fall Time	t _f			25		
Source - Drain Diode Characteristics						
Diode Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 8A			1.4	V
Diode Continuous Forward Current	I _S	Integral reverse p-n Junction diode in the MOSFET			8	A
Body Diode Reverse Recovery Time	t _{rr}	I _S =8A, dI/dt = 100 A/μs, V _{GS} = 0V		235		ns
Body Diode Reverse Recovery Charge	Q _{rr}				1.85	

Notes :

1. Drain current is limited by maximum junction temperature.
2. Repetitive rating : pulse width limited by junction temperature.
3. L = 40mH, I_{AS} = 4.5A, V_{DD} = 100V, R_G=25Ω, Starting at T_J = 25°C

Typical Characteristics

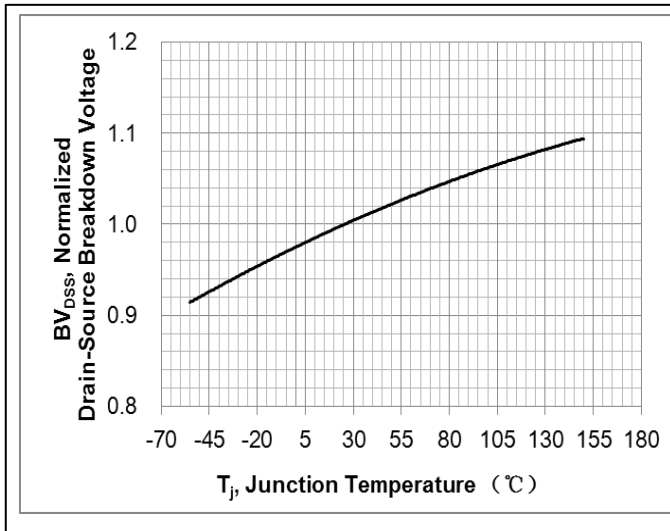


Fig1. BV_{DSS} vs Junction Temperature

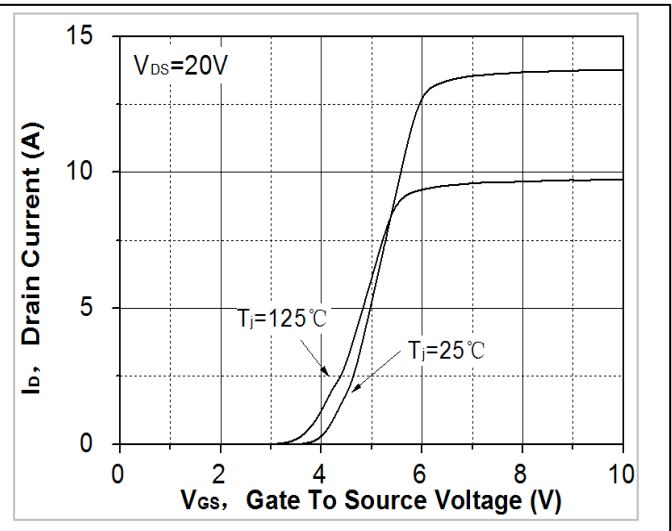


Fig2. Transfer characteristics

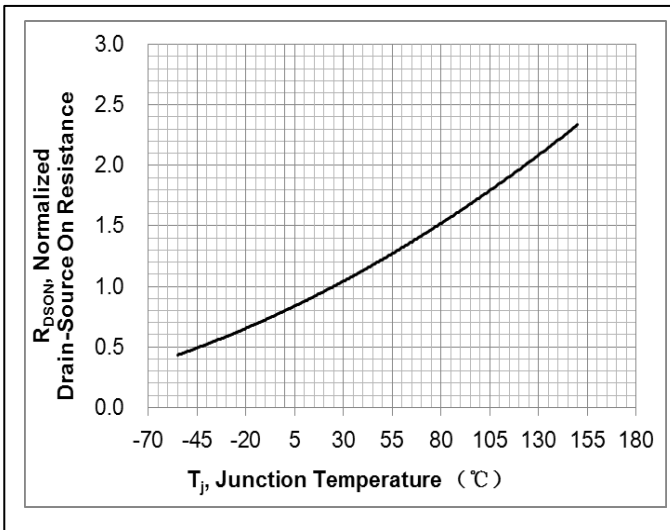


Fig3. $R_{DS(ON)}$ vs Junction Temperature

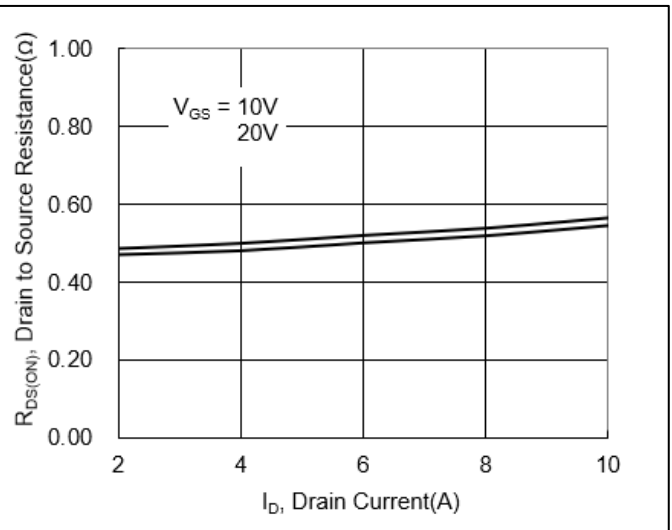


Fig4. Drain-source on-state resistance

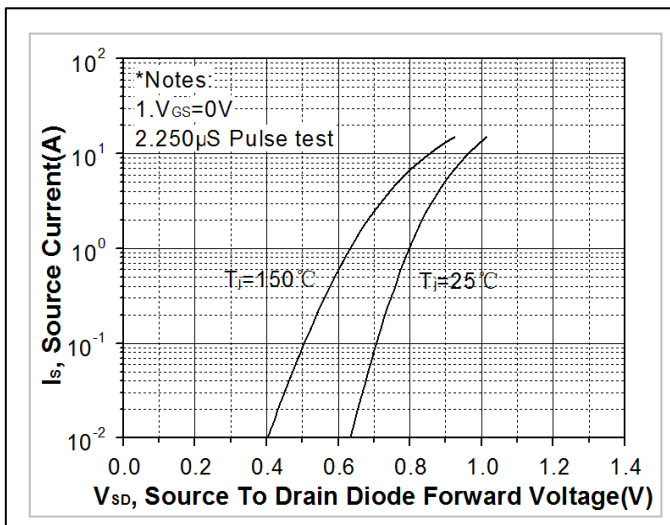


Fig5. Forward characteristics of reverse diode

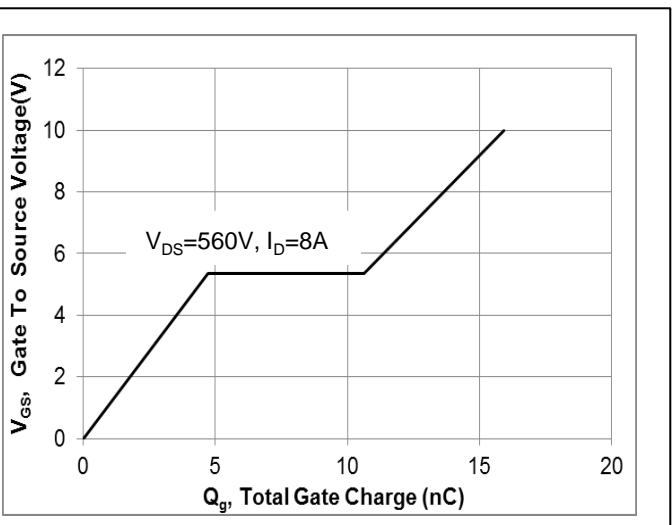


Fig6. Gate charge characteristics

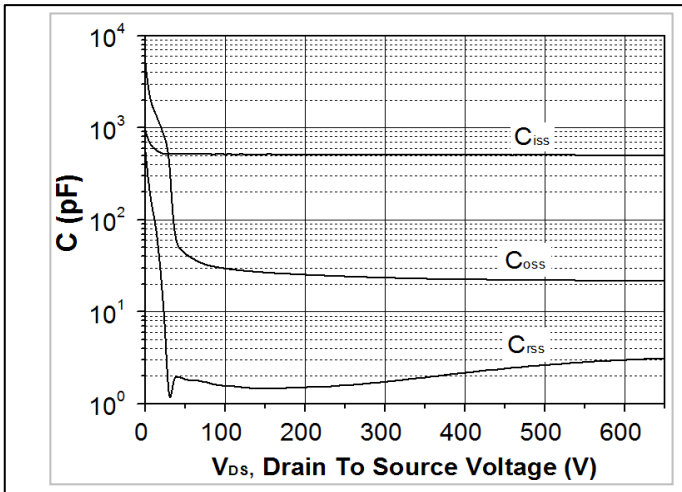


Fig 7. Capacitance Characteristics

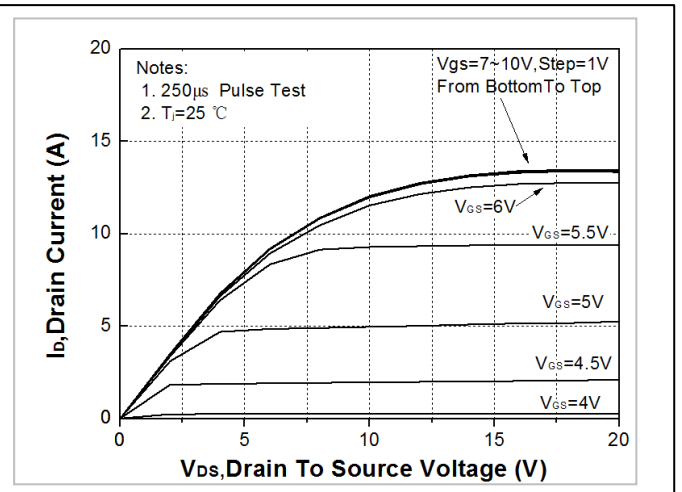


Fig 8. Output characteristics (T_J=25 °C)

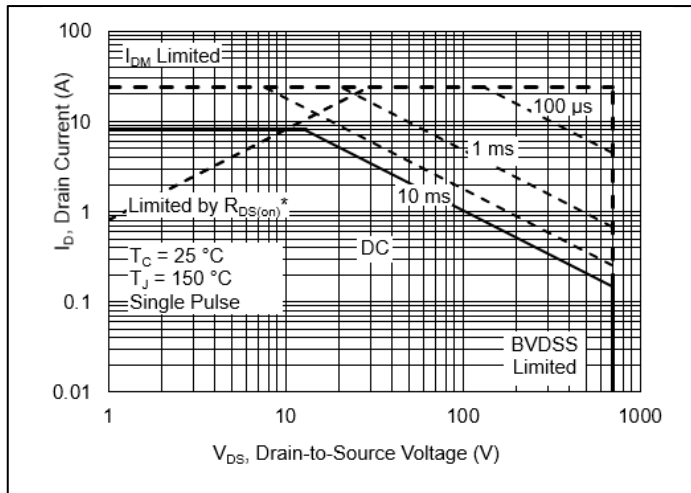


Fig 9. Safe operating area(TO-252)

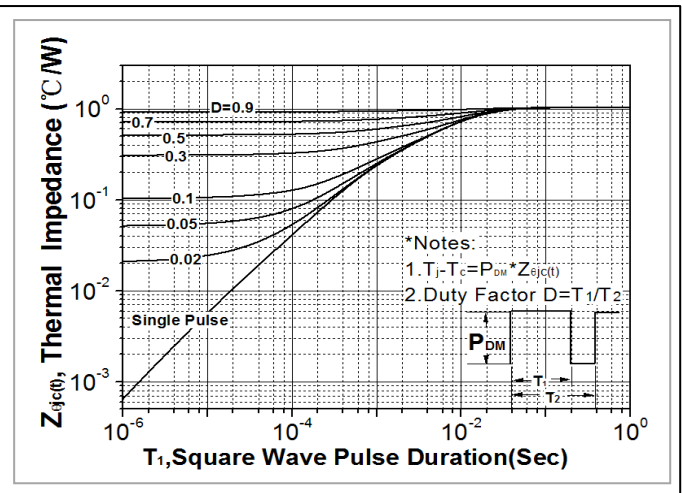
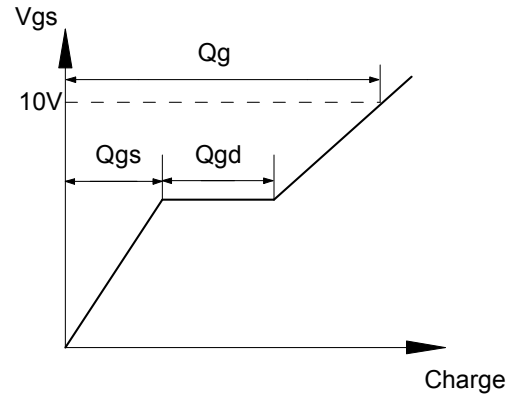
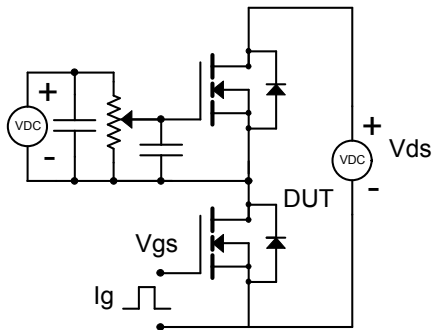
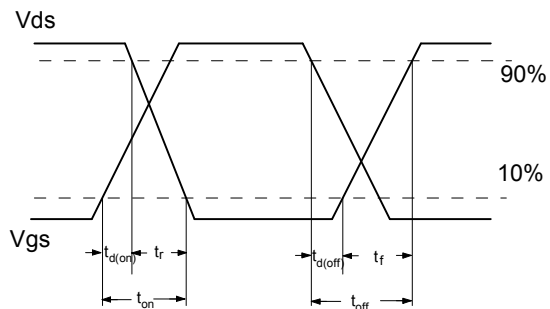
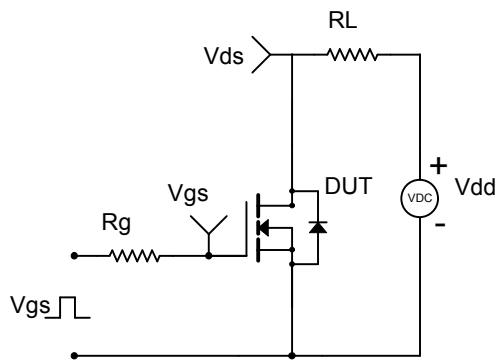


Fig 10. Transient thermal impedance (TO-252)

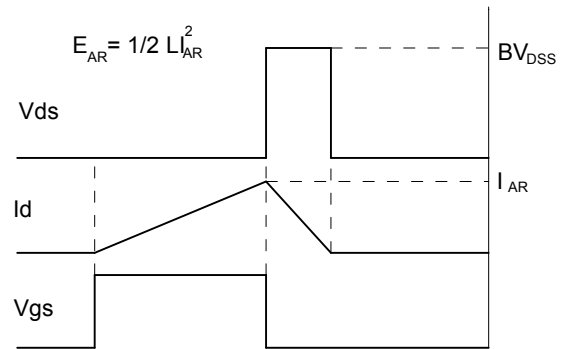
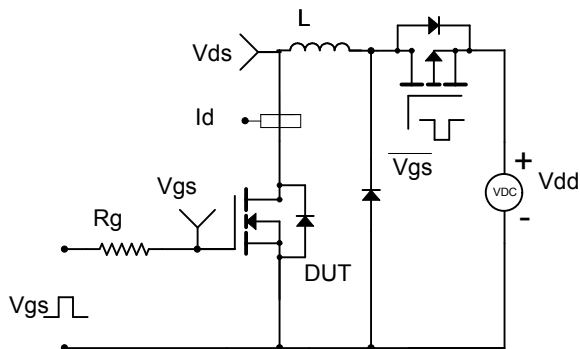
Gate Charge Test Circuit & Waveform



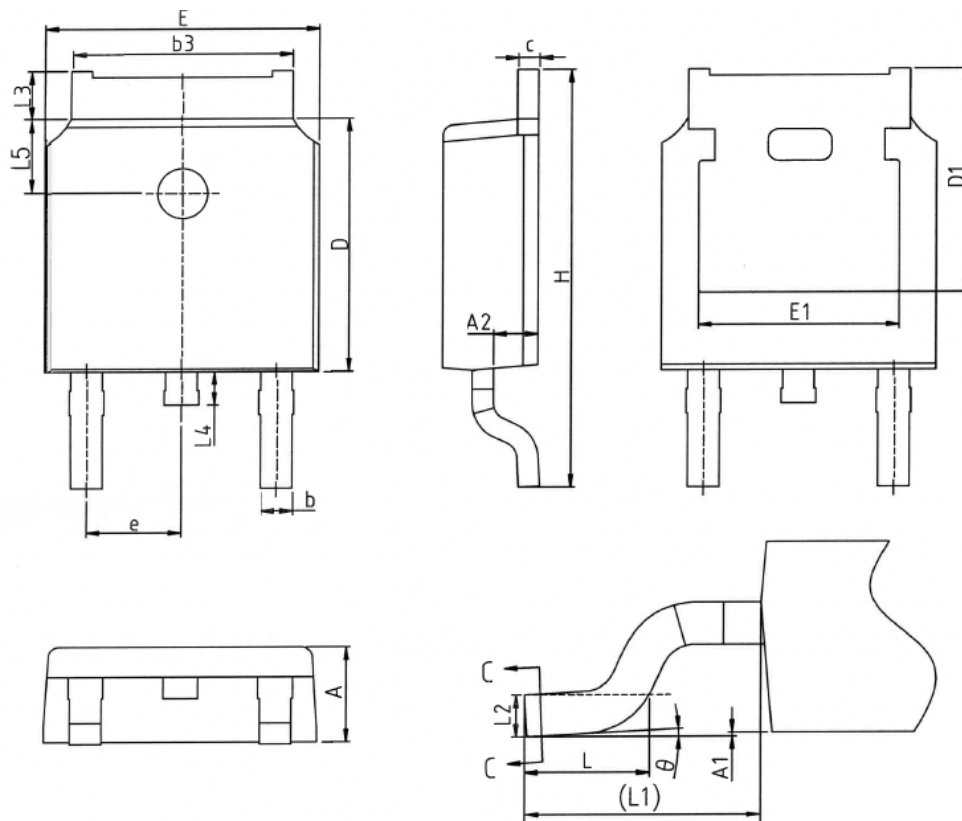
Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



TO-252-2L Package Information



NOTES
 1. ALL DIMENSIONS REFER TO JEDEC STANDARD TO-252 AA,
 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

SYMBOL	mm		
	MIN	NOM	MAX
A	2.20	2.30	2.38
A1	0.00	-	0.12
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b3	5.20	5.33	5.46
c	0.43	0.53	0.61
D	5.98	6.10	6.22
D1	5.30REF		
E	6.40	6.60	6.73
E1	4.63	-	-
e	2.286BSC		
H	9.40	10.10	10.50
L	1.38	1.50	1.75
L1	2.90REF		
L2	0.51BSC		
L3	0.88	-	1.28
L4	0.50	-	1.00
L5	1.65	1.80	1.95
θ	0°	-	8°

Attention:

- GreenPower Electronics reserves the right to improve product design function and reliability without notice.
- Any and all semiconductor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.
- GreenPower Electronics products belong to consumer electronics or other civilian electronic products.